



FINAL PRODUCT/PROCESS CHANGE NOTIFICATIONGeneric Copy

08-Jan-2008**SUBJECT: ON Semiconductor Final Product/Process Change Notification #16086****TITLE: Final Notification for ON Semiconductor Zero Delay Buffer Backend Processing****PROPOSED FIRST SHIP DATE: 08-Apr-2008****AFFECTED CHANGE CATEGORY(S): Backend Packaging Process****AFFECTED PRODUCT DIVISION(S): Analog Clock and Data Products****FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Gregg Hooker < gregg.hooker@onsemi.com >**SAMPLES:** Contact your local ON Semiconductor Sales Office**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Matt Kas < Matt.Kas@onsemi.com >**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is the FPCN to IPCN 15741 available at www.onsemi.com ON Semiconductor will be manufacturing backend assembly and test process for the Zero Delay Buffer products. Electrical datasheet parameters and specifications will not change. This qualification will allow ON Semiconductor to meet the increasing demand for these types of devices. During the qualification, a design fix was implemented to prevent a potential problem with customer applications operating between a 15 and 30 MHz frequency range. Product with a date code of 0743 or later represents the design tweak. Prior inventory was purged. The backend processing will be performed at the ON Semiconductor OSPI facility in Carmona Philippines.

**Final Product/Process Change Notification #16086****RELIABILITY DATA SUMMARY:****Reliability Test Results:**

Extrinsic Reliability Testing performed on a sample size of 1 lot with 80 pieces/lot. This supports a TSSOP 16 package qualification effort on a previously qualified package at OSPI.

Test	Conditions	Results
High Temp Op Life (HTOL)	Ta =125DegC for 504 hours	Pass 0/80
MSL-1 Bake (PC)	24hr Bake at 125DegC, +168Hr 85% RH at 60DegC	
MSL-1 at 260C (PC)	3IR at 260DegC	
PC Autoclave (AC)	Ta=121DegC/100% RH/15 PSIG for 96 Hours	Pass 0/80
PC-Temp Cycling (TC)	-65DegC to +150DegC; for 500 cycles	Pass 0/80
SAT	ON Semiconductor SAT Guidelines	Pass 0/10

ELECTRICAL CHARACTERISTIC SUMMARY:

Characterization data will be available upon request.

CHANGED PART IDENTIFICATION:

All Zero Delay Buffers with a date code including and after 0743 represent the new design fix.

**Final Product/Process Change Notification #16086****AFFECTED DEVICE LIST****PART**

NB2304AI1DG
NB2304AI1HDG
NB2304AI2DG
NB2304AI1DR2G
NB2304AI1HDR2G
NB2304AI2DR2G
NB2305AI1DG
NB2305AI1HDG
NB2305AI1DR2G
NB2305AI1HDR2G
NB2305AI1DTG
NB2305AI1HDTG
NB2305AI1DTR2G
NB2305AI1HDTR2G
NB2308AI1DG
NB2308AI1HDG
NB2308AI1DR2G
NB2308AI1HDR2G
NB2308AI1DTG
NB2308AI1HDTG
NB2308AI1DTR2G
NB2308AI1HDTR2G
NB2308AI2DG
NB2308AI2HDG
NB2308AI2DTG
NB2308AI2HDTG
NB2308AI2DR2G
NB2308AI2HDR2G
NB2308AI2DTR2G
NB2308AI2HDTR2G
NB2308AI3DG
NB2308AI3DTG
NB2308AI3DR2G
NB2308AI3DTR2G
NB2308AI4DG
NB2308AI4DTG
NB2308AI4DR2G
NB2308AI4DTR2G
NB2308AI5HDG
NB2308AI5HDTG
NB2308AI5HDR2G
NB2308AI5HDTR2G
NB2309AI1DG
NB2309AI1DTG
NB2309AI1HDG
NB2309AI1HDTG
NB2309AI1DR2G
NB2309AI1DTR2G
NB2309AI1HDR2G
NB2309AI1HDTR2G